

Multi-Beam activity from the 1980s

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Multi-Beam Concepts for Nanometer Devices

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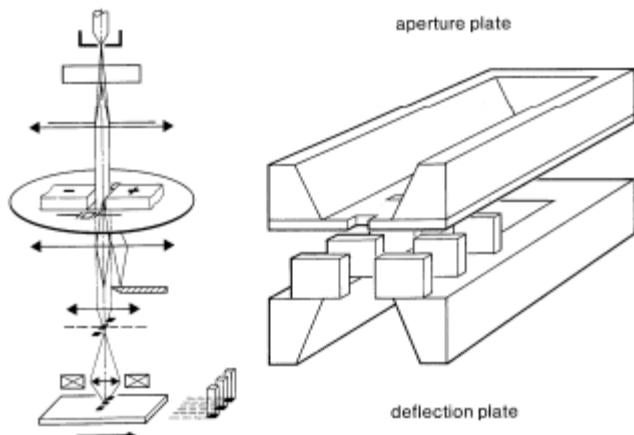


Fig. 8. Control plate, consisting of a probe forming aperture plate and a deflection plate for individual beam blanking.

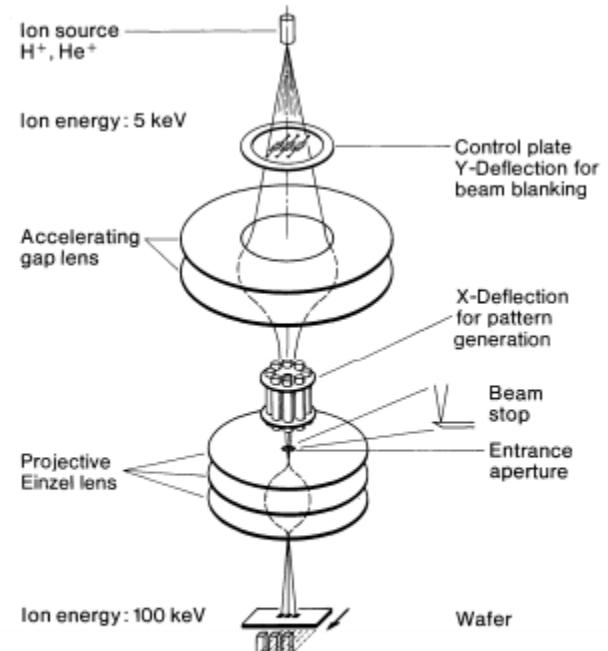


Fig. 14. Ion beam stepper with modifications (control plate, ribbon beam illumination, beam stop) for multi beam applications (by permission of IMS, Vienna, Austria).



Jiun Sonja (1718-1805)
Buji Kore Kinin
“Only those who live simply,
live nobly”
Genzō Hattori Collection

Multi-Beam Mask Writer

Hans Loeschner

IMS Nanofabrication AG
Vienna, Austria

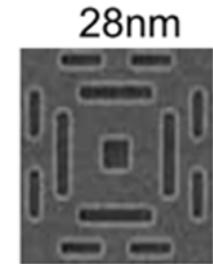
Apr 18, 2013



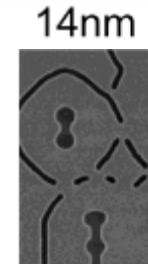
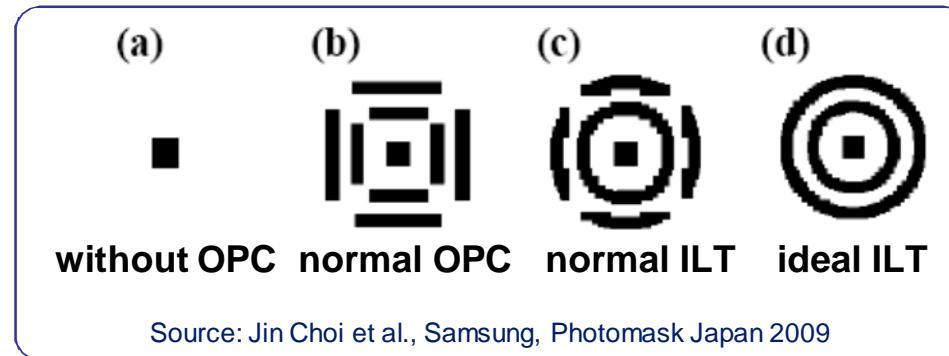
Kobori Sōchū (1786-1867)
Mei Rekireki Ro Dōdō
“Everything lies openly before us,
plainly and undisguised”
Genzō Hattori Collection

SMO (Source Mask Optimization) with OPC and ILT

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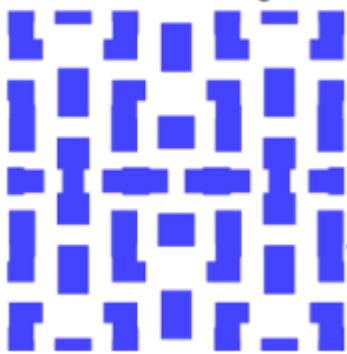
Source: Samsung



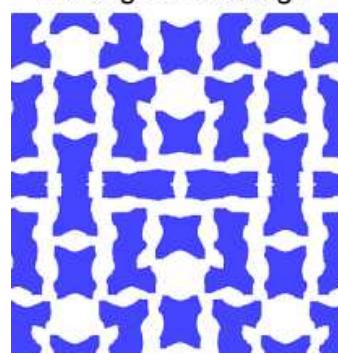
Source: DNP

Optical Proximity Correction

Bias OPC design



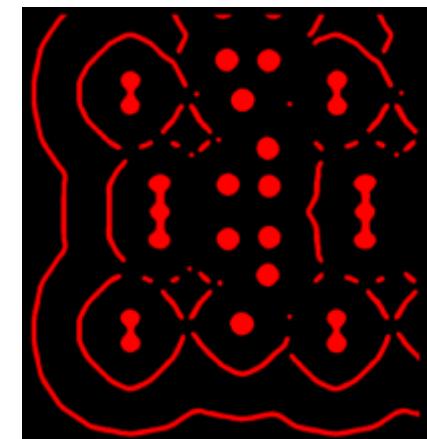
Strong OPC design



⇒ improved DOF

Source: Naoya Hayashi, DNP, LithoVision 2012

Inverse Lithography Technology



Source: Naoya Hayashi, DNP



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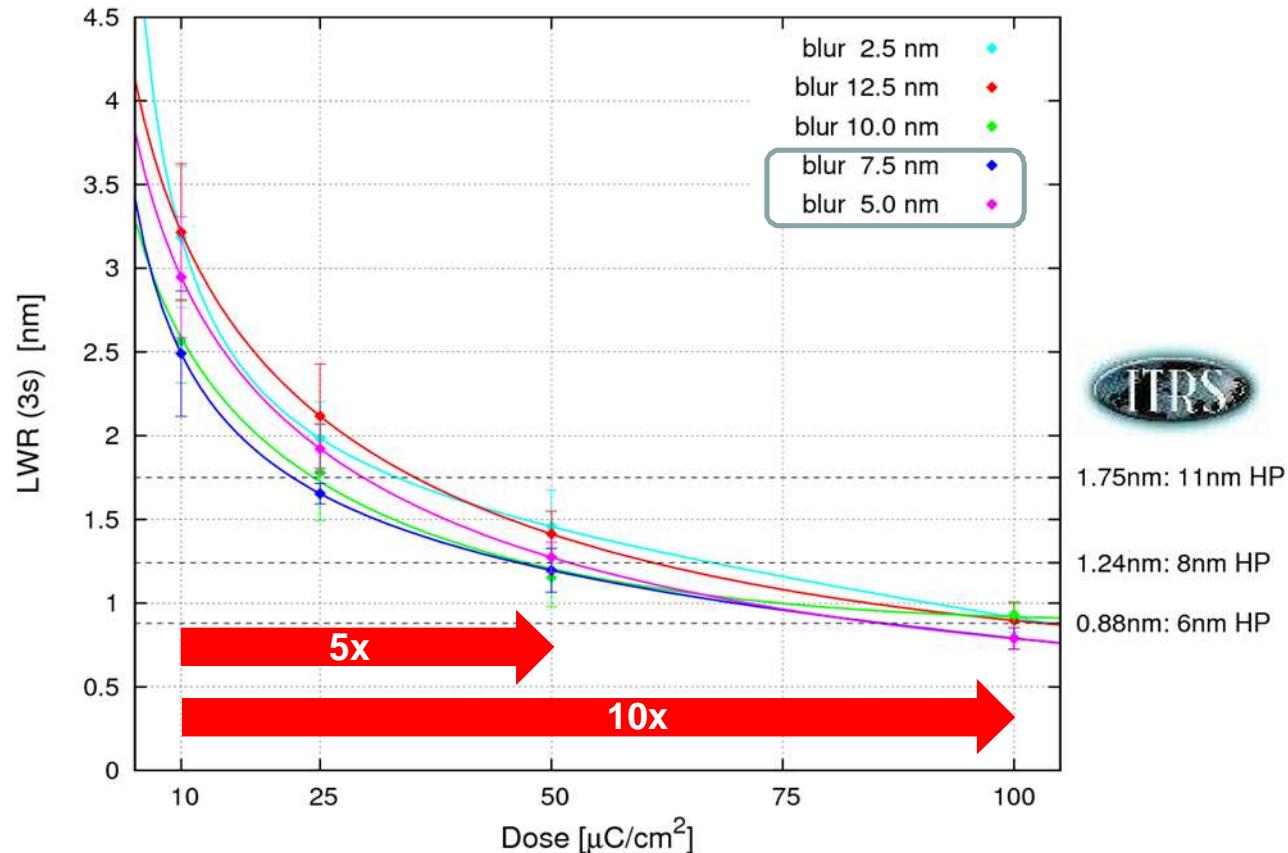
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Exposure Dose

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LWR Monte Carlo simulation results for CD = 30nm



For the 11nm HP mask technology node and below
resist exposure dose must be increased by a factor of 5 to 10



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VSB vs MB

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50keV electron Variable Shaped Beam (VSB) Mask Writer

beams: 1

Shape size: variable

Current density: 800 A/cm²

Current: 80nA / 100nm square
3.2nA / 20nm square
0.8nA / 10nm square

50keV electron Multi-Beam (MB) Mask Writer

beams: 262,144 (512 x 512)

Beam size: fixed, 20nm, 10nm, ...

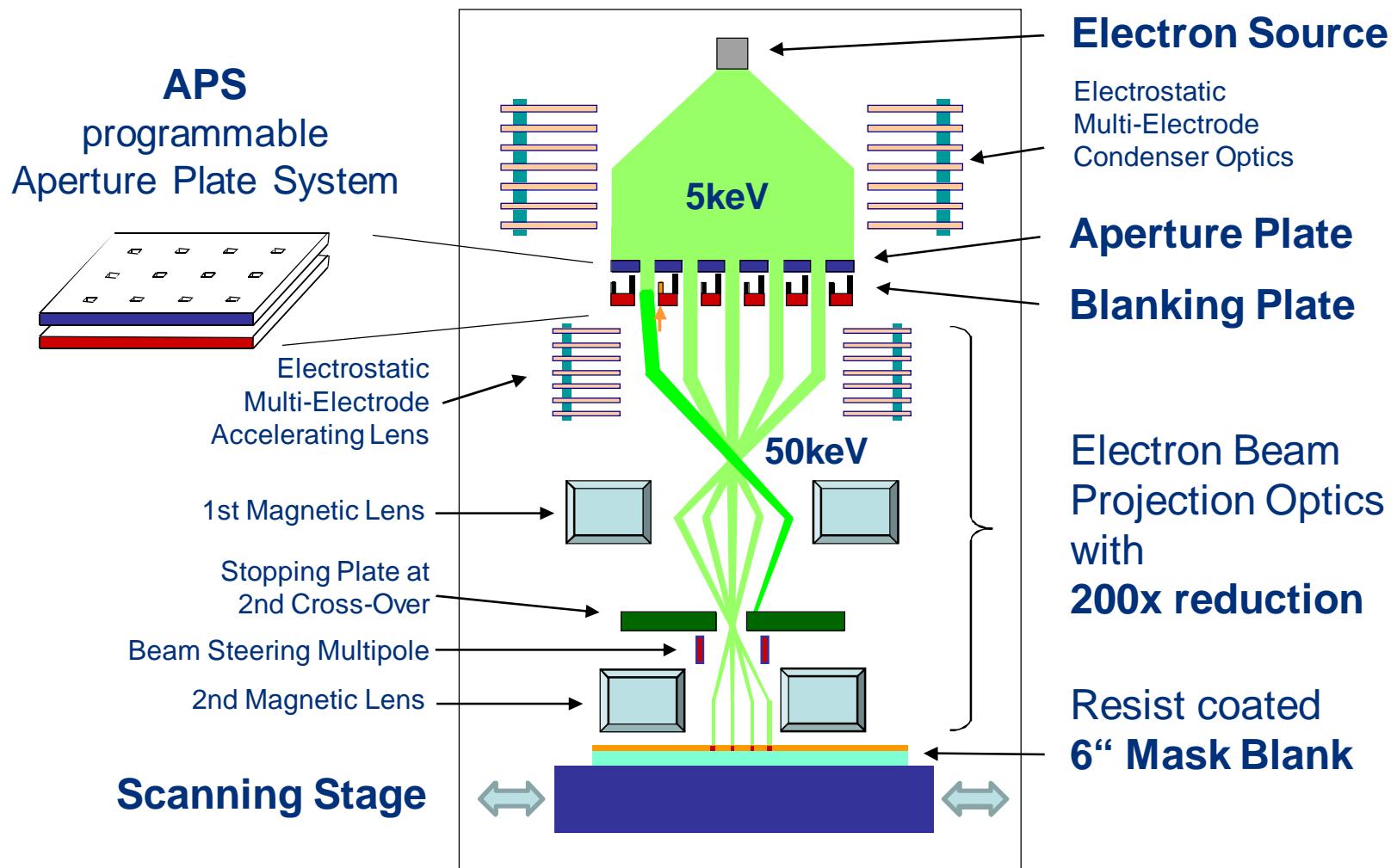
Current density: 1 A/cm² / 20nm beam
4 A/cm² / 10nm beam

Current:
(all beams “on”) 1 μA / 20nm beam
1 μA / 10nm beam



MB Mask Writer Tool Principles

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[8680-19]

SPIE - ALT 5 / Feb 26, 2013

eMET POC – Proof-of-Concept electron Mask Exposure Tool

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- # of programmable beams:** 262,144
- Data Path:** 12.8 Gbits/s
- Beam energy:** 50keV
- Beam size:** 20nm
- Column Blur:** 5nm 1sigma
- Address grid:** 0.1nm
- Writing:** Scanning stage
- Current:** 0.1 μ A - 1 μ A
- TPT:** up to 10cm²/h



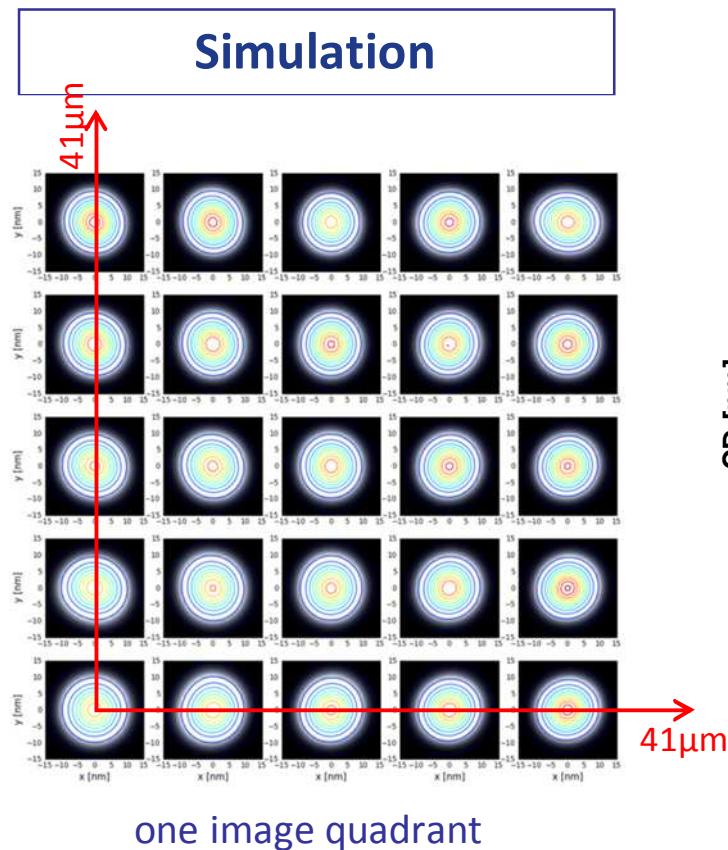
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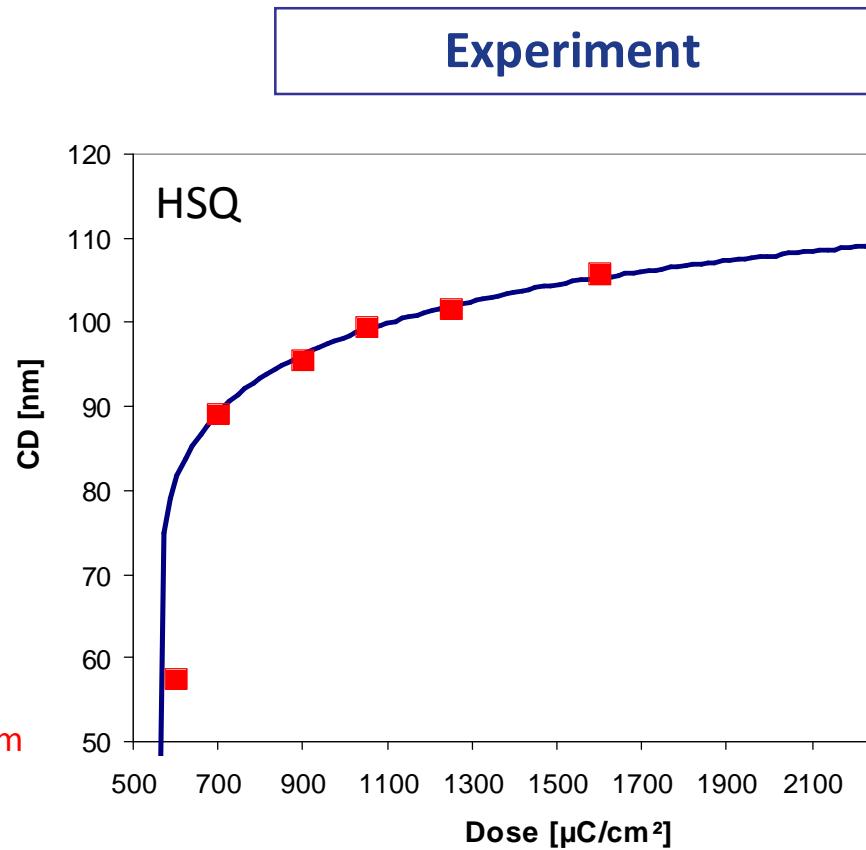
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MB Column Blur: 5nm 1sigma

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Simulated 1sigma blur:
5.3 nm
@ 82μm x 82μm beam array field



Measured 1sigma blur (incl. resist):
6.65 nm (Center); at Corners:
– 0.45nm, 0.02nm, 0.045nm, 0.70nm

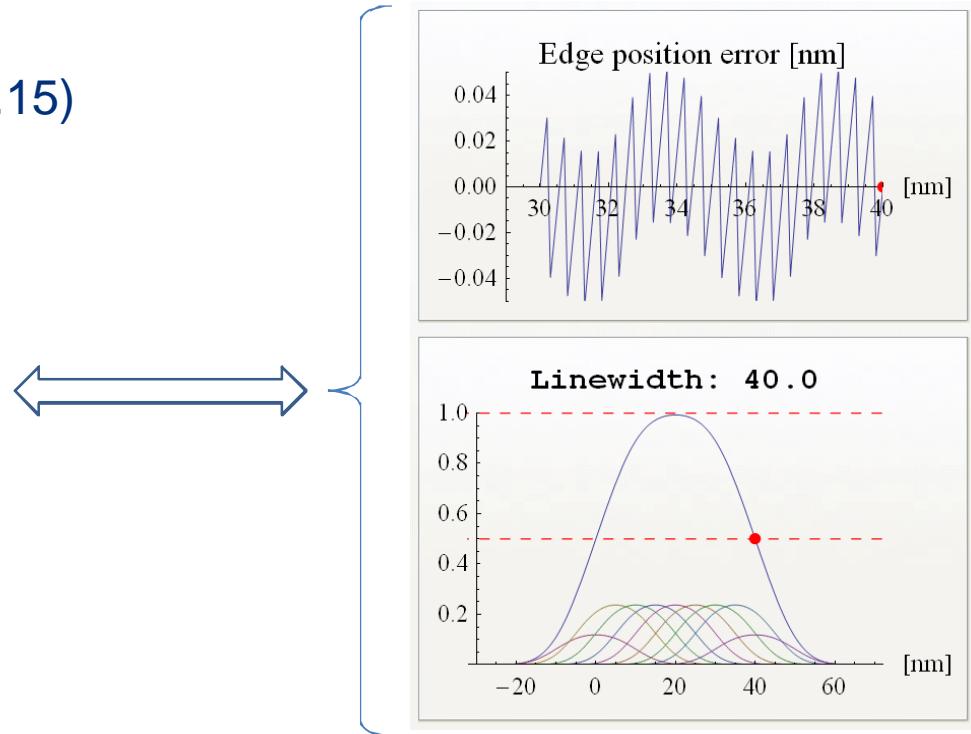
0.1nm Address Grid by MESA (Multiple Exposure Shot Addressing)

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□ Overlapping Shots: Pixel = $\frac{1}{4}$ Beam Size

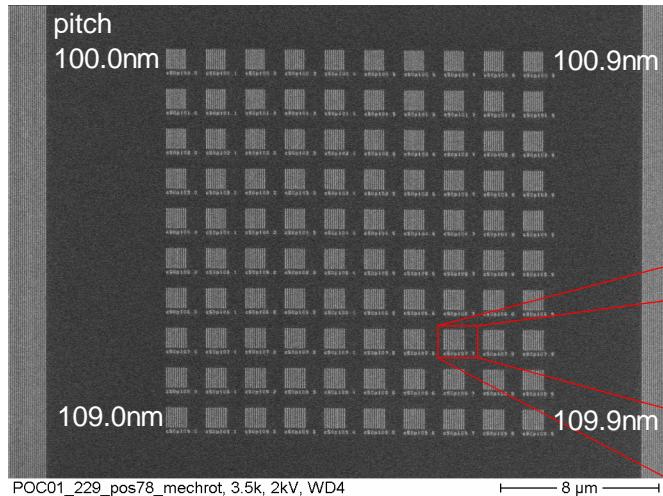
□ Every 20nm shot exposed with
4bit = 16 dose levels (0, 1, 2,...,15)

Beam Size: 20 nm
Pixel Size: 5 nm
⇒
 $16 \times 15 + 1: 241$ dose levels / area
 $4 \times 15 + 1: 61$ dose levels / edge



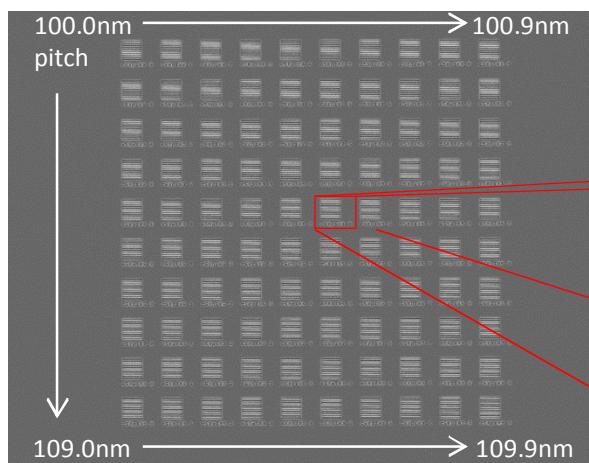
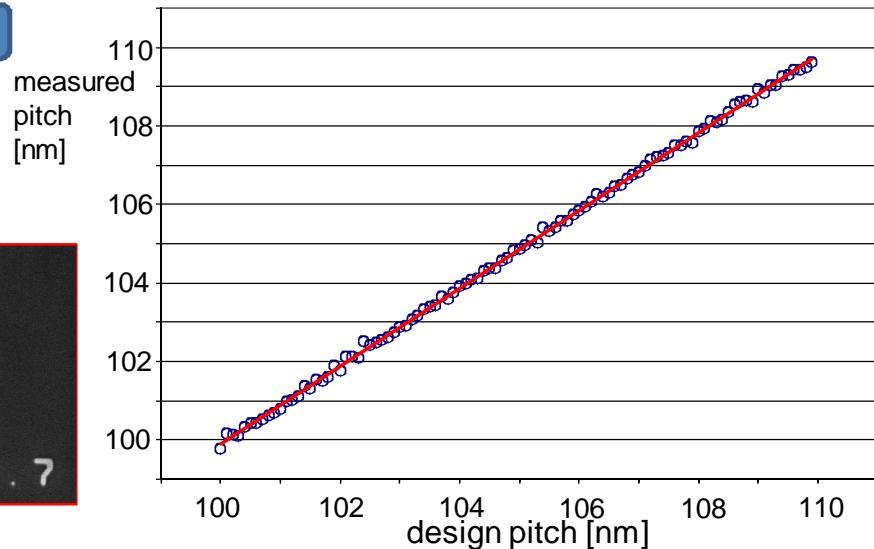
Multi-Beam Writing @ 0.1nm Address Grid

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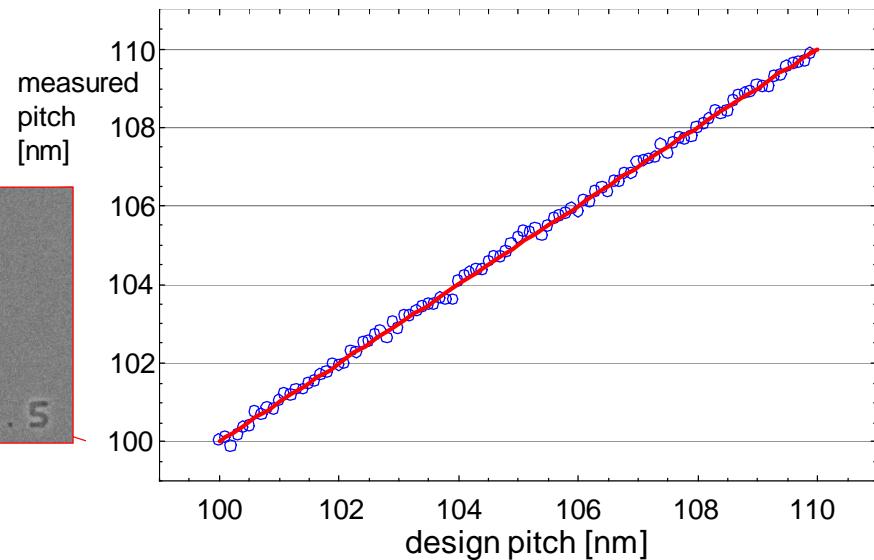
BACUS 2012

HSQ



SPIE 2013

PCAR



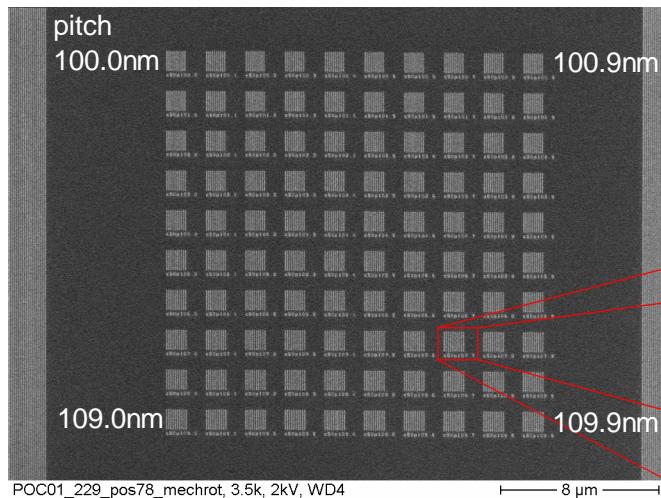
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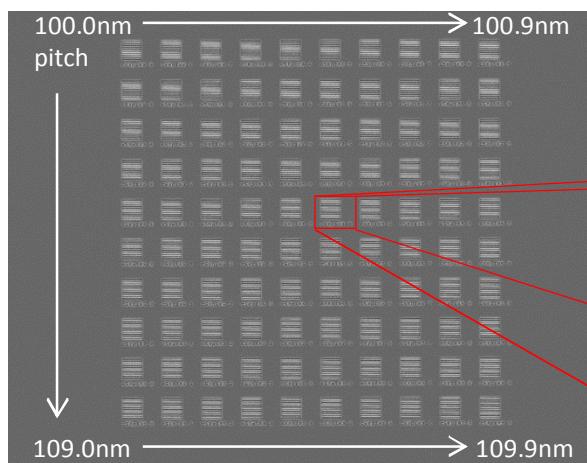
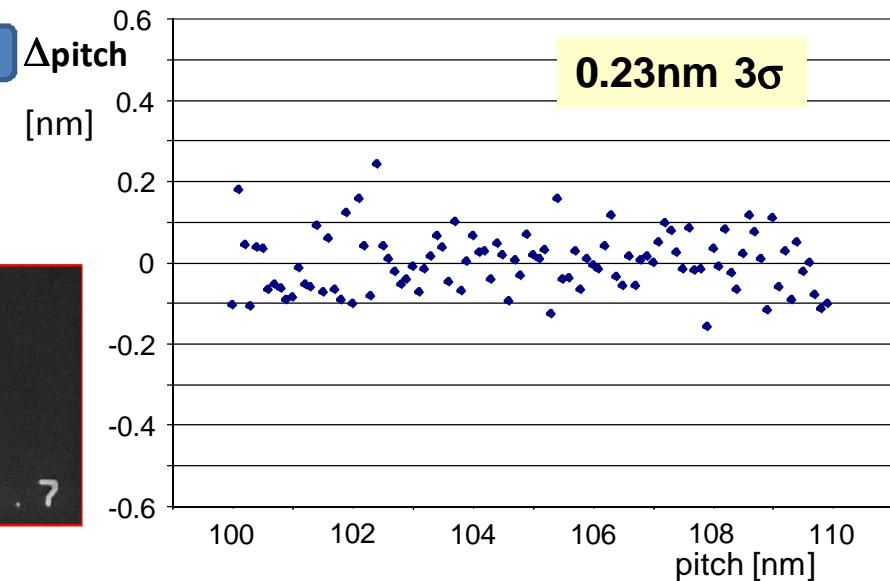
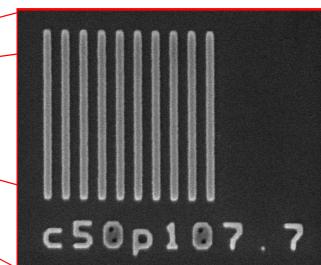
Multi-Beam Writing @ 0.1nm Address Grid

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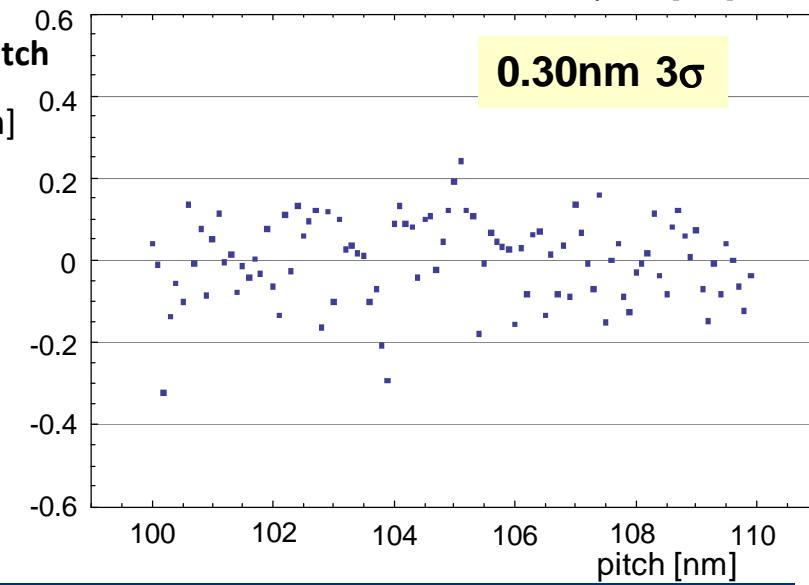
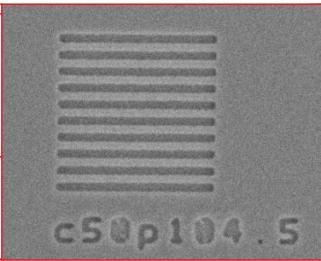
BACUS 2012

HSQ



SPIE 2013

PCAR



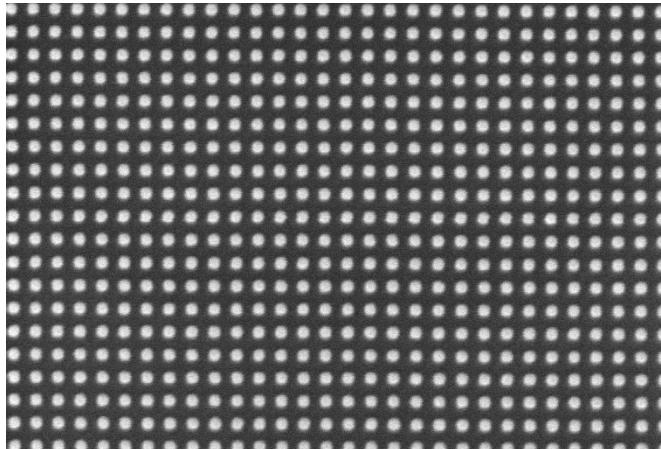
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40nm Dots with at slightly modified grid

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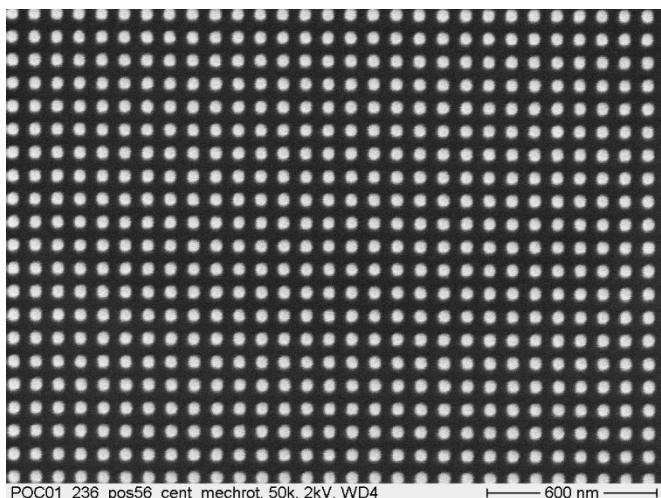
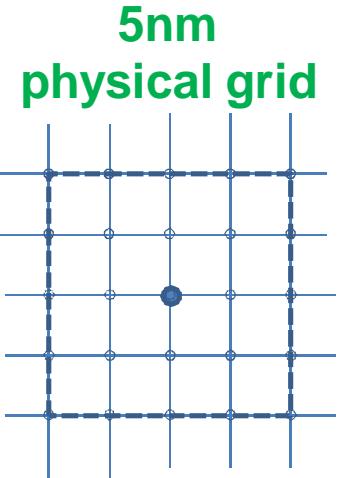


40nm dots with 80nm pitch

LCDU = 1.63nm 3sigma

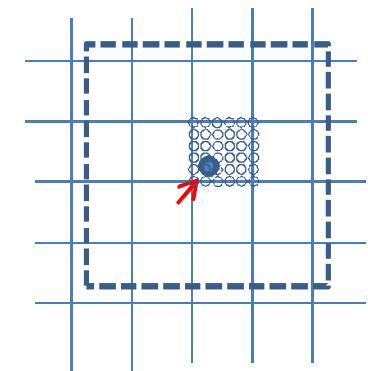
64 shots per dot!

Every dot on equivalent grid position



40nm dots with 81nm pitch

LCDU = 1.61nm 3sigma



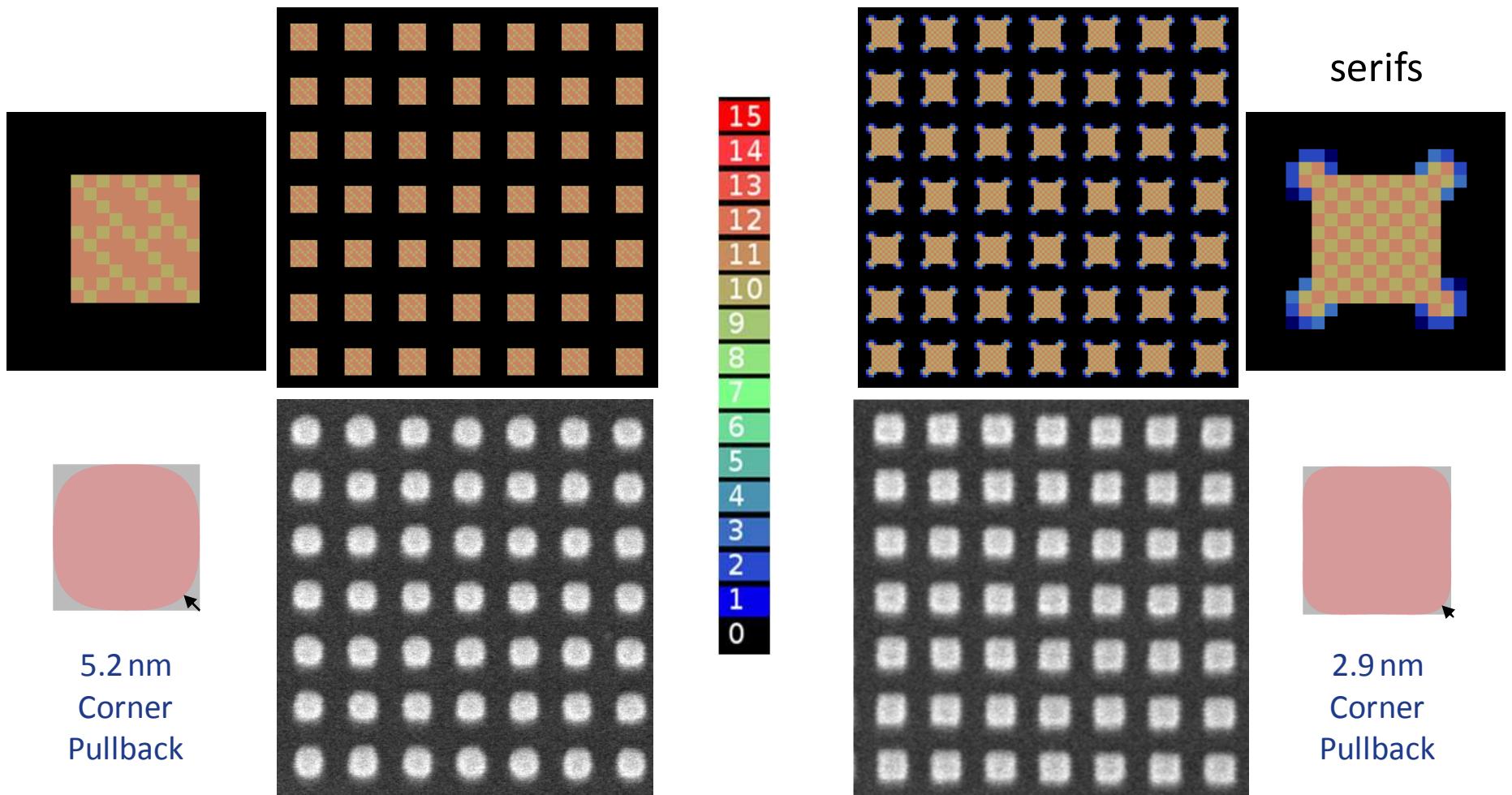
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Corner Radius Improvement

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Additional Shots are NOT degrading TPT



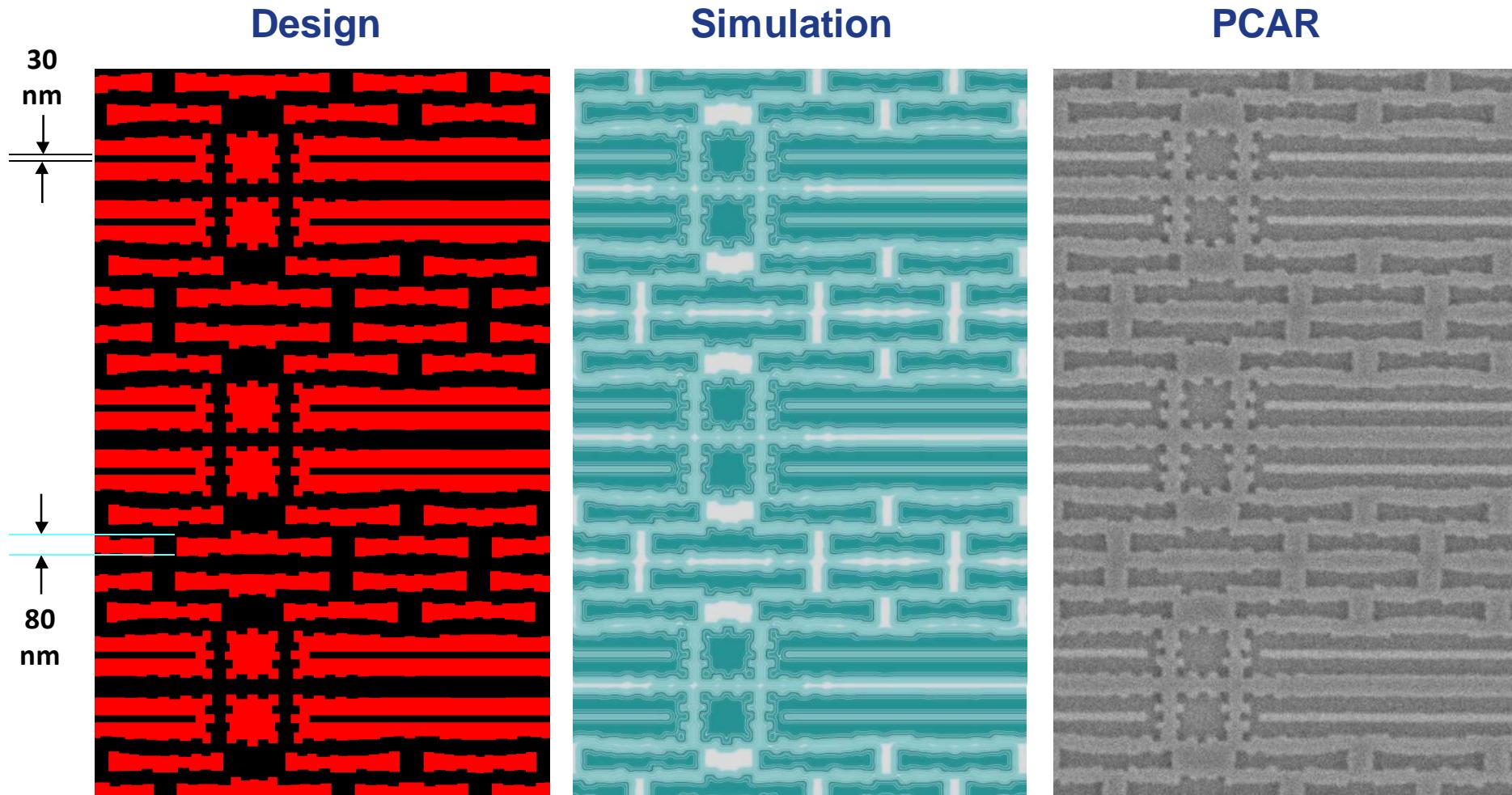
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Exposure of aggressive OPC Pattern

14



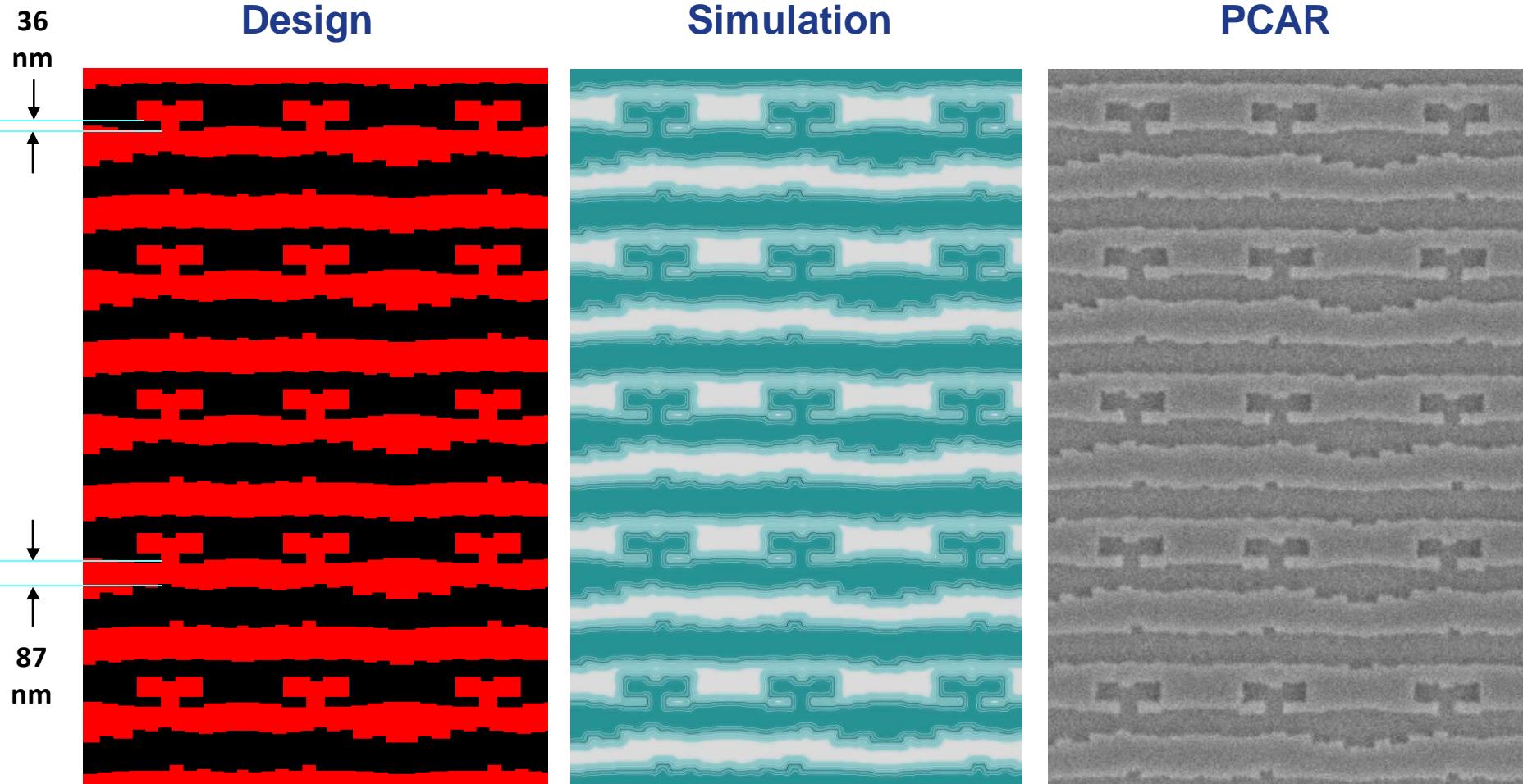
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Exposure of aggressive OPC Pattern

15



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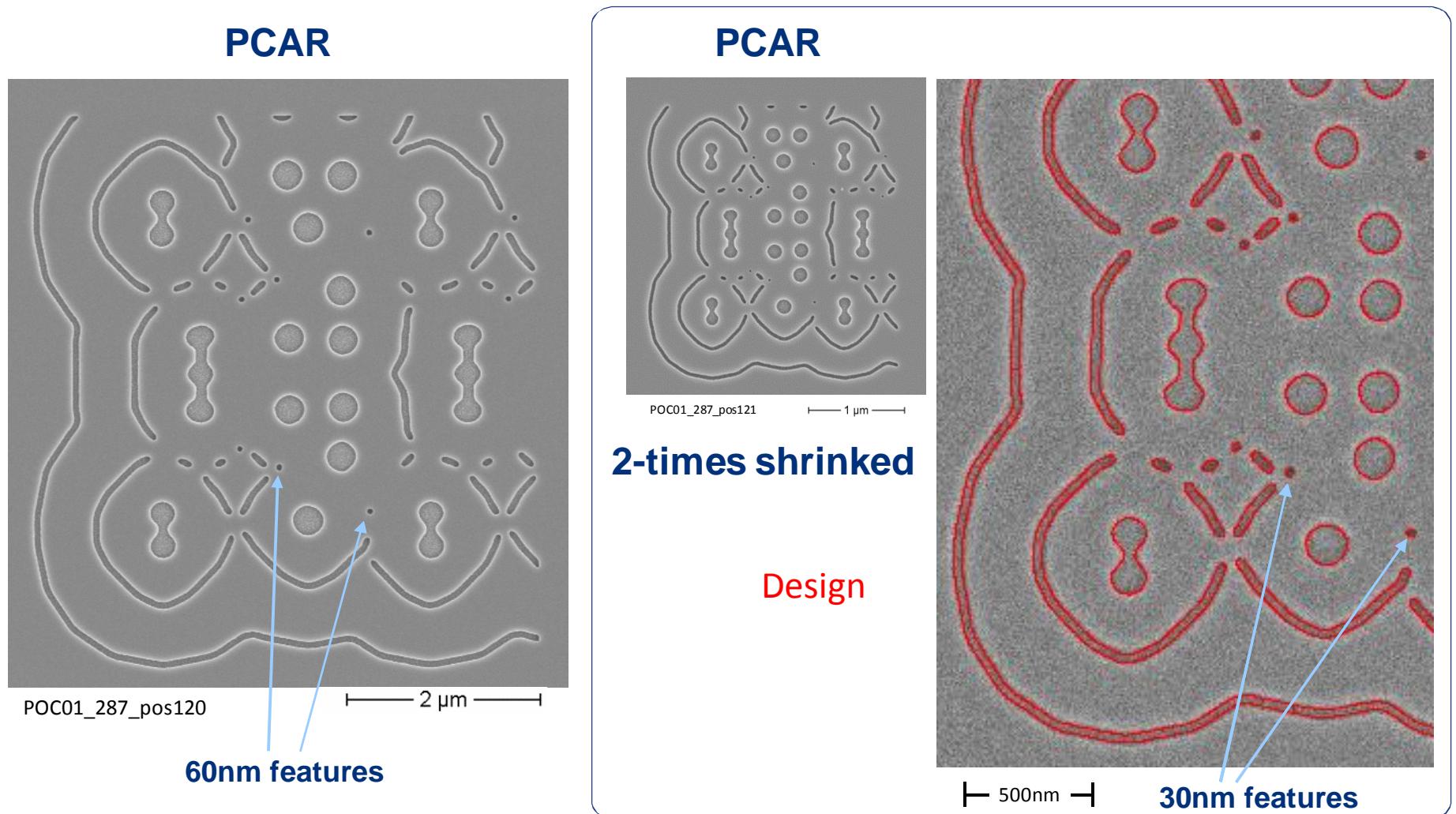
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Exposure of ILT test pattern

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ILT design: DNP



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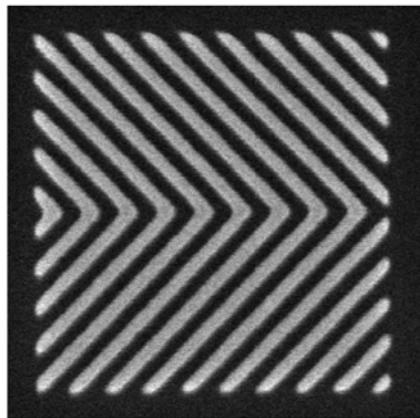
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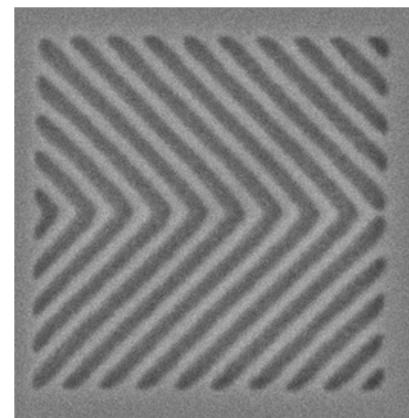
Realized MB Column: Extendibility to sub-10nm nodes

17

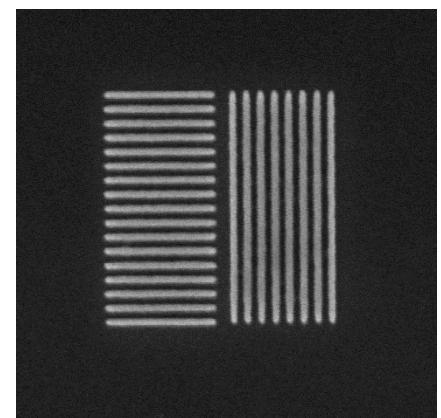
**30nm HP in HSQ
negative resist**



**30nm HP in PCAR
positive resist**



**24nm HP in HSQ
negative resist**



50keV electron multi-beam exposure with 20nm beam size



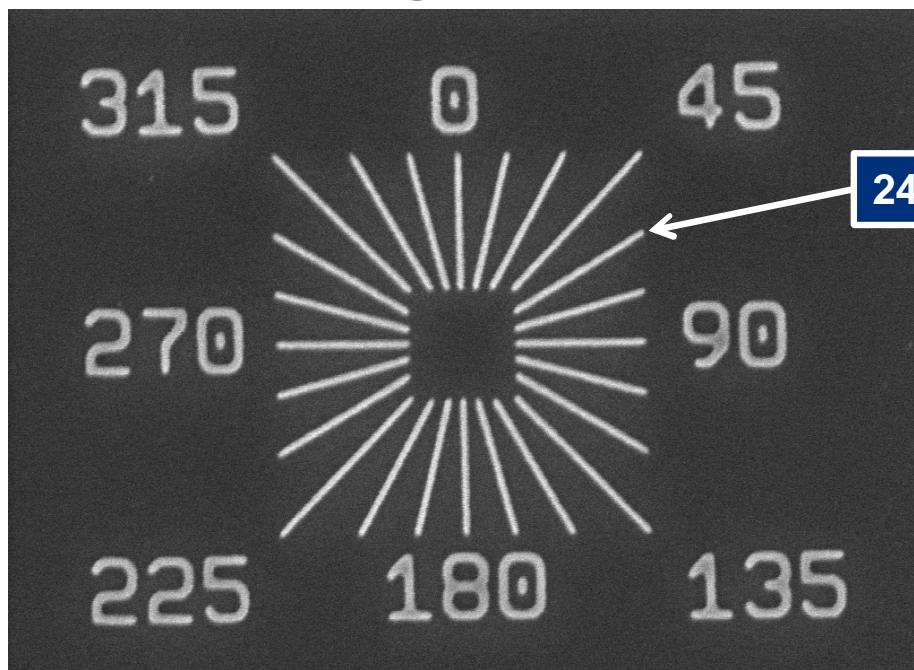
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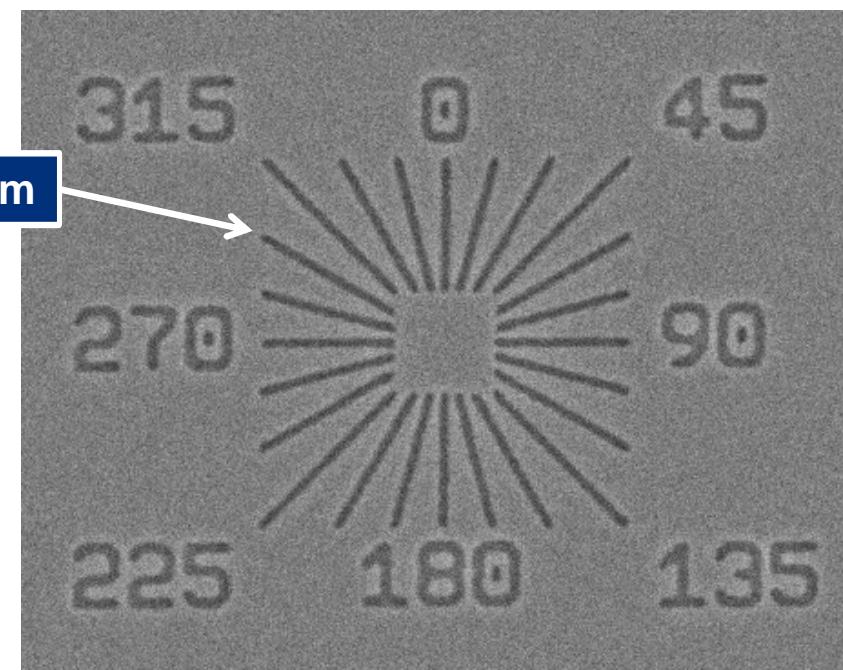
24nm any angle iso lines

HSQ negative resist



POC01_291_pos102

PCAR positive resist



POC01_292_pos055

50keV electron multi-beam exposure with 20nm beam size



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Multi-Beam Mask Writer Roadmap

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	POC	ALPHA	BETA	1st gen. HVM
	2012	2014	2015	2016
Technology Node	Test: 11nm HP (7nm Logic)	11nm HP (7nm Logic)	11nm HP (7nm Logic)	11nm HP (7nm Logic)
Beam Array Field	82µm x 82µm	82µm x 82µm	82µm x 82µm	82µm x 82µm
# Beams	262,144	262,144	262,144	262,144
max Current (all beams “on”)	0.1 - 1 µA	1 µA	1 µA	1 µA
Throughput ($\geq 100\mu\text{C}/\text{cm}^2$)	<10 cm ² /h	15h/mask	10h/mask	10h/mask



Thank You for Your Attention !

Kawai Gyukudō (1873-1957)
Shōrai Zensei
“The Rustling of the Pine Tree,
the Voice of the Cicada”
Genzō Hattori Collection